

Micropower 50 mA Ultra Low-Dropout Regulator

Features

- Ultra low dropout voltage
- Output voltage accuracy 0.5% (A Grade)
- Guaranteed 50mA output current
- Smallest possible size (SOT-23, micro SMD package)
- Requires only 1 µF external capacitance
- < 1 µA quiescent current when shutdown
- Low ground pin current at all load currents
- High peak current capability (150mA typical)
- Wide supply voltage range (16V max)
- Fast dynamic response to line and load
- Low ZOUT over wide frequency range
- Over temperature/over current protection
- -40°C to +125°C junction temperature range



Ordering Information

DEVICE	Package Type	MARKING	Packing	Packing Qty
LP2980IM5-3.0/TR	SOT-23-5	L02B	REEL	3000pcs/Reel
LP2980IM5-3.3/TR	SOT-23-5	L00B	REEL	3000pcs/Reel
LP2980IM5-5.0/TR	SOT-23-5	L01B	REEL	3000pcs/Reel
LP2980AIM5-3.0/TR	SOT-23-5	L02A	REEL	3000pcs/Reel
LP2980AIM5-3.3/TR	SOT-23-5	L00A	REEL	3000pcs/Reel
LP2980AIM5-5.0/TR	SOT-23-5	L01A	REEL	3000pcs/Reel



General Description

The LP2980 is a 50mA, fixed-output voltage regulator designed specifically to meet the requirements of battery-powered applications. Using an optimized VIP[™] (Vertically Integrated PNP) process, the LP2980 delivers unequaled performance in all specifications critical to battery-powered designs:

Dropout Voltage. Typically 120mV @ 50mA load, and 7mV @ 1mA load.

Ground Pin Current. Typically 375 $\mu A \ensuremath{\,@}\xspace$ 50mA load, and 80 $\mu A \ensuremath{\,@}\xspace$ 1mA load.

Sleep Mode. Less than 1 μA quiescent current when ON/ OFF pin is pulled low.

Smallest Possible Size. SOT-23 and micro SMD packages use an absolute minimum board space.

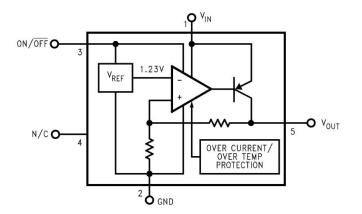
Minimum Part Count. Requires only 1 µF of external capacitance on the regulator output.

Precision Output. 0.5% tolerance output voltages available (A grade). 5.0V, 3.3V, and 3.0V versions available as standard products.

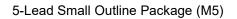
Applications

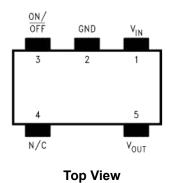
- Cellular Phone
- Palmtop/Laptop Computer
- Personal Digital Assistant (PDA)
- Camcorder, Personal Stereo, Camera

Block Diagram



Connection Diagram







Absolute Maximum Ratings(Note 1)

Condition	Min	Мах	
Storage Temperature Range	-65°C	+150°C	
Operating Junction Temperature Range	-40°C	+125°C	
Lead Temperature (Soldering, 10sec.)	-	245°C	
ESD Rating (Note 2)	- 2kV		
Power Dissipation (Note 3)	Internally Limited		
Input Supply Voltage (Survival)	-0.3V +16V		
Input Supply Voltage (Operating)	2.1V +16V		
Shutdown Input Voltage (Survival)	-0.3V +16V		
Output Voltage (Survival) (Note 4)	-0.3V +9V		
I _{OUT} (Survival)	Short Circuit Protected		
Input-Output Voltage (Survival) (Note 5)	-0.3V	+16V	

Electrical Characteristics

Limits in standard typeface are for $T_J = 25^{\circ}C$, and limits in **boldface type** apply over the full operating temperature range. Unless otherwise specified: $V_{IN} = V_{O(NOM)} + 1V$, $I_L = 1mA$, $C_{OUT} = 1\mu$ F, $V_{ON/OFF} = 2V$.

Symbol	Parameter	Conditions	Тур	LP2980AI-XX (Note 6)		LP2980I-XX (Note 6)		Units	
				Min	Max	Min	Max		
	Output Voltage	I∟ = 1mA		-0.50	0.50	-1.0	1.0		
ΔVo	Tolerance	1mA < I∟ < 50mA		-0.75 -2.5	0.75 2.5	-1.5 -3.5	1.5 3.5	%V _{№ОМ}	
ΔVO ΔVIN	Output Voltage Line Regulation	V _{O(NOM)} + 1V ≤V _{IN} ± 16V	0.007 0.014 0.032			0.014 0.032	%/V		
		I _L = 0	1		3 5		3 5		
	V _{IN} –V _o (Note 7)	I _L = 1mA	7		10 15		10 15		
VIN-VO		I _L = 10mA	40		60 90		60 90	mV	
		I∟ = 50mA	120		150 225		150 225		
	Ground Pin Current $I_L = 1$	I _L = 0	65		95 125		95 125		
I _{GND}		I _L = 1mA	80		110 170		110 170	μΑ	
		I _L = 10mA	140		220 460		220 460		



		I _L = 50mA	375		600 1200		600 1200		
		$V_{ON/OFF} < 0.18V$	0		1		1		
N	ON/OFF Input Voltage	High = O/P ON	1.4	1.6		1.6		V	
Von/off	(Note 8)	Low = O/P OFF	0.55		0.18		0.18	V	
		Von/off = 0	0		-1		-1		
I _{ON/OFF}	ON/OFF Input Current	V _{ON/OFF} = 5V	5	15			15	μA	
I _{O(PK)}	Peak Output Current	$V_{OUT} \ge V_{O(NOM)} - 5\%$	150	100		100		mA	
en	Output Noise Voltage (RMS)	BW = 300 Hz–50 kHz, C _{OUT} = 10 μF	160					μV	
ΔVIN ΔVO	Ripple Rejection	f = 1 kHz C _{ουτ} = 10 μF	63					dB	
I _{O(MAX)}	Short Circuit Current	R _L = 0 (Steady State) (Note 9)	150					mA	

Note 1: Absolute maximum ratings indicate limits beyond which damage to the component may occur. Electrical specifications do not apply when operating the device outside of its rated operating conditions.

Note 2: The ESD rating of pins 3 and 4 is 1kV.

Note 3: The maximum allowable power dissipation is a function of the maximum junction temperature, TJ(MAX), the junction-to-ambient thermal resistance, θ JA, and the ambient temperature, TA. The maximum allowable power dissipation at any ambient temperature is calculated using:

$$P(MAX) = \frac{TJ(MAX) - TA}{\theta JA}$$

The value of θJA for the SOT-23 package is 220°C/W and the micro SMD package is 320°C/W. Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown.

Note 4: If used in a dual-supply system where the regulator load is returned to a negative supply, the LP2980 output must be diode-clamped to ground.

Note 5: The output PNP structure contains a diode between the VIN and VOUT terminals that is normally reverse-biased. Reversing the polarity from VIN to VOUT will turn on this diode (see Application Hints).

Note 6: Limits are 100% production tested at 25°C. Limits over the operating temperature range are guaranteed through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate National's Average Outgoing Quality Level (AOQL).

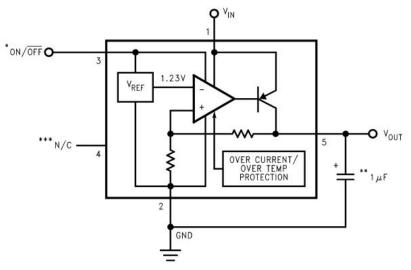
Note 7: Dropout voltage is defined as the input to output differential at which the output voltage drops 100mV below the value measured with a 1V differential.

Note 8: The ON/OFF inputs must be properly driven to prevent misoperation. For details, refer to Application Hints.

Note 9: See Typical Performance Characteristics curves.



Basic Application Circuit



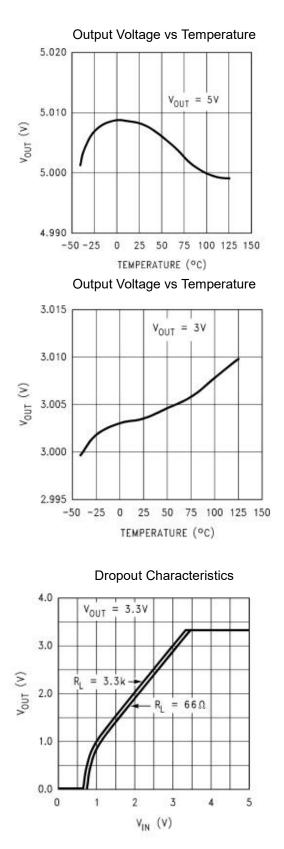
*ON/OFF input must be actively terminated. Tie to VIN if this function is not to be used.

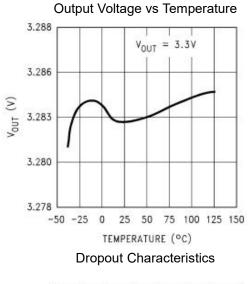
**Minimum Output Capacitance is 1 μF to insure stability over full load current range. More capacitance provides superior dynamic performance and additional stability margin (see Application Hints).

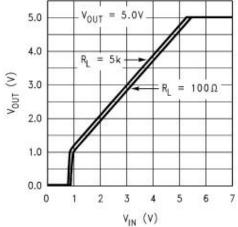
***Do not make connections to this pin.

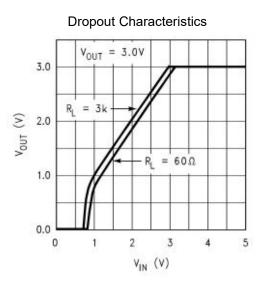


Unless otherwise specified: TA = 25°C, VIN = VO(NOM) + 1V, COUT = 2.2 µF, all voltage options, ON/OFF pin tied to VIN.

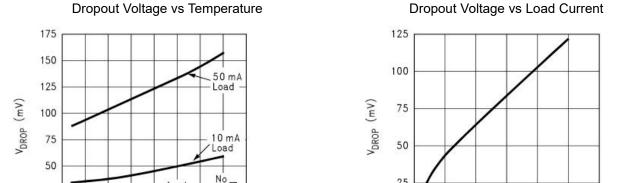




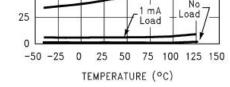




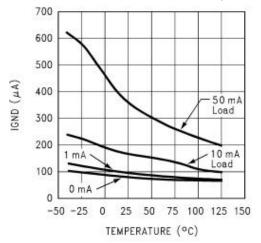




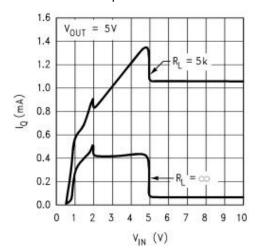
Unless otherwise specified: TA = 25°C, VIN = VO(NOM) + 1V, COUT = 2.2 µF, all voltage options, ON/OFF pin tied to VIN (Continued)

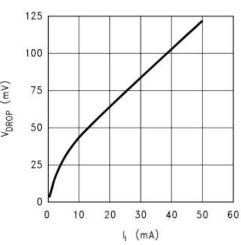




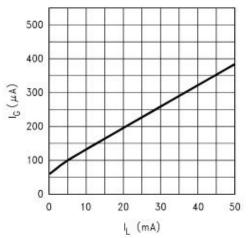


Input Current vs VIN

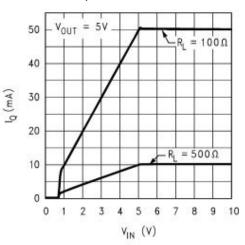




Ground Pin Current vs Load Current

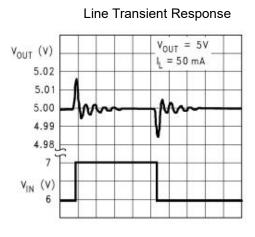


Input Current vs VIN

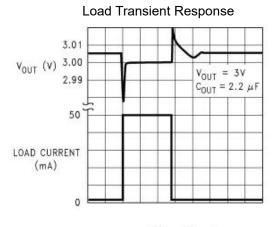




Unless otherwise specified: TA = 25°C, VIN = VO(NOM) + 1V, COUT = 2.2 µF, all voltage options, ON/OFF pin tied to VIN (Continued)

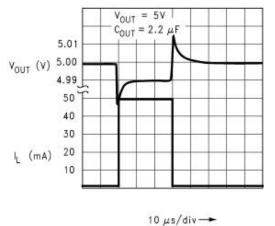


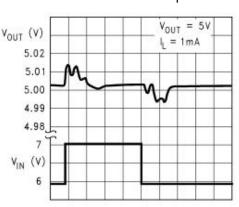
20 µs/div ---



10 µs/div→

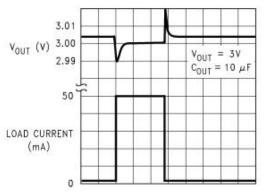






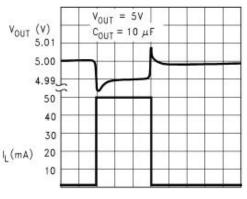
20 µs/div ---

Load Transient Response



10 µs/div→

Load Transient Response

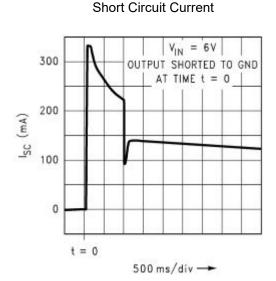


10 µs/div →

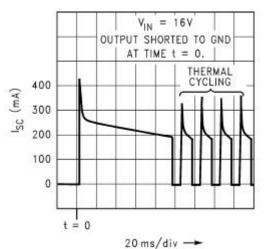
Line Transient Response



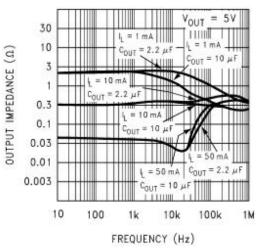
Unless otherwise specified: TA = 25°C, VIN = VO(NOM) + 1V, COUT = 2.2 µF, all voltage options, ON/OFF pin tied to VIN (Continued)



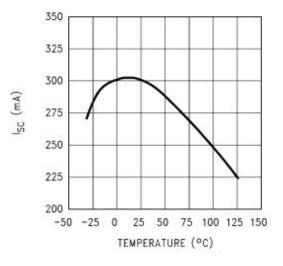
Short Circuit Current



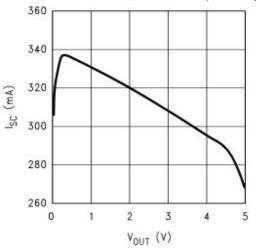
Output Impedance vs Frequency



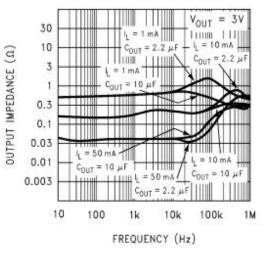
Instantaneous Short Circuit Current vs Temperature



Instantaneous Short Circuit Current vs Output Voltage

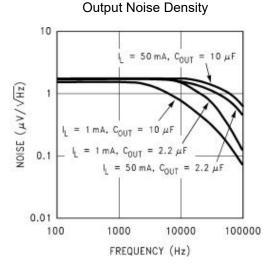


Output Impedance vs Frequency

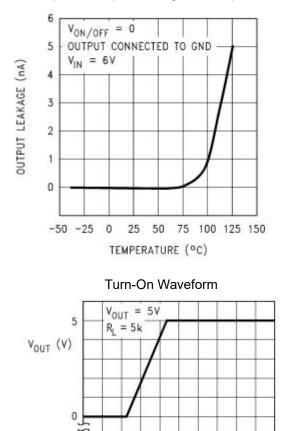




Unless otherwise specified: TA = 25°C, VIN = VO(NOM) + 1V, COUT = 2.2 µF, all voltage options, ON/OFF pin tied to VIN (Continued)



Input to Output Leakage vs Temperature

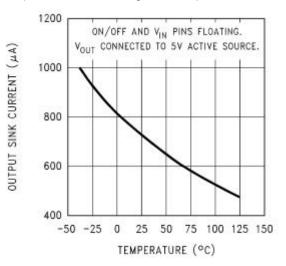


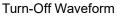
20 µs/div →

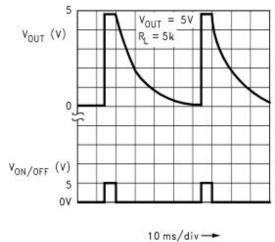
 $V_{OUT} = 3V$ 80 RIPPLE REJECTION (dB) = 2.2 COUT 1 mA 60 = 10 0111 1 mA 40 $C_{OUT} = 10 \ \mu F$ = 50 mA ų 20 $C_{OUT} = 2.2 \,\mu F$ 50 mA 0 10 100 100k 1k 10k 1M FREQUENCY (HZ)

Ripple Rejection

Output Reverse Leakage vs Temperature







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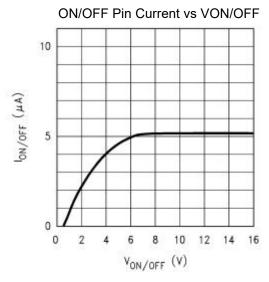
VON/OFF (V)

57

٥V



Unless otherwise specified: TA = 25°C, VIN = VO(NOM) + 1V, COUT = 2.2 µF, all voltage options, ON/OFF pin tied to VIN (Continued)



Application Hints

OUTPUT CAPACITOR

Like any low-dropout regulator, the LP2980 requires an output capacitor to maintain regulator loop stability. This capacitor must be selected to meet the requirements of minimum capacitance and equivalent series resistance (ESR) range. It is not difficult to find capacitors which meet the criteria of the LP2980, as the acceptable capacitance and ESR ranges are wider than for most other LDOs.

In general, the capacitor value must be at least 1 μ F (over the actual ambient operating temperature), and the ESR must be within the range indicated in Figures 1, 2 and Figure 3. It should be noted that, although a maximum ESR is shown in these Figures, it is very unlikely to find a capacitor with ESR that high.

Tantalum Capacitors

Surface-mountable solid tantalum capacitors offer a good combination of small physical size for the capacitance value, and ESR in the range needed by the LP2980.

The results of testing the LP2980 stability with surface-mount solid tantalum capacitors show good stability with values of at least 1 μ F. The value can be increased to 2.2 μ F (or more) for even better performance, including transient response and noise.

Small value tantalum capacitors that have been verified as suitable for use with the LP2980 are shown in Table 2. Capacitance values can be increased without limit.

Aluminum Electrolytic Capacitors

Although probably not a good choice for a production design, because of relatively large physical size, an aluminum electrolytic capacitor can be used in the design prototype for an LP2980 regulator. A value of at least 1 μ F should be used, and the ESR must meet the conditions of Figures 1, 2 and Figure 3. If the operating temperature drops below 0°C, the regulator may not remain stable, as the ESR of the aluminum electrolytic capacitor will increase, and may exceed the limits indicated in the Figures.



TABLE 2. Surface-Mount Tantalum Capacitor Selection Guide

1 μF Surface-Mount Tantalums							
Manufacturer	Part Number						
Kemet	T491A105M010AS						
NEC	NRU105M10						
Siemens	B45196-E3105-K						
Nichicon	F931C105MA						
Sprague	293D105X0016A2T						
2.2 µF Surface-Mount Tantalums							
Manufacturer	Part Number						
Kemet	T491A225M010AS						
NEC	NRU225M06						
Siemens	B45196/2.2/10/10						
Nichicon	F930J225MA						
Sprague	293D225X0010A2T						

Multilayer Ceramic Capacitors

Surface-mountable multilayer ceramic capacitors may be an attractive choice because of their relatively small physical size and excellent RF characteristics. However, they sometimes have ESR values lower than the minimum required by the LP2980, and relatively large capacitance change with temperature. The manufacturer's datasheet for the capacitor should be consulted before selecting a value.

Test results of LP2980 stability using multilayer ceramic capacitors show that a minimum value of 2.2 μ F is usually needed for the 5V regulator. For the lower output voltages, or for better performance, a higher value should be used, such as 4.7 μ F.

Multilayer ceramic capacitors that have been verified as suitable for use with the LP2980 are shown in Table 3.

TABLE 3. Surface-Mount Multilayer Ceramic Capacitor Selection Guide

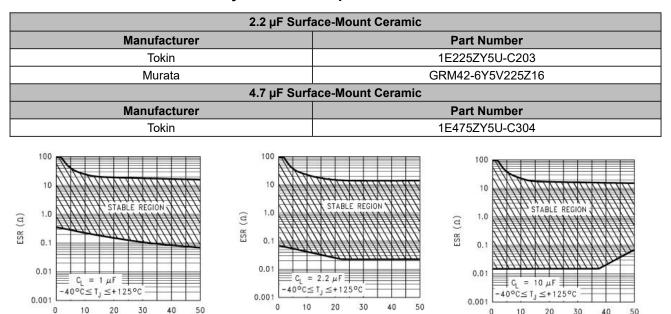


FIGURE 1. 1 µF ESR Range

LOAD CURRENT (mA)

FIGURE 2. 2.2 µF ESR Range

LOAD CURRENT (mA)

FIGURE 3. 10 µF ESR Range

LOAD CURRENT (mA)



REVERSE CURRENT PATH

The power transistor used in the LP2980 has an inherent diode connected between the regulator input and output (see below).

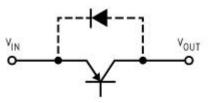


FIGURE 4. LP2980 Reverse Current Path

If the output is forced above the input by more than a VBE, this diode will become forward biased and current will flow from the VOUT terminal to VIN. No damage to the LP2980 will occur under these conditions as long as the current flowing into the output pin does not exceed 100mA.

ON/OFF INPUT OPERATION

The LP2980 is shut off by pulling the ON/OFF input low, and turned on by driving the input high. If this feature is not to be used, the ON/OFF input should be tied to VIN to keep the regulator on at all times (the ON/OFF input must not be left floating).

To ensure proper operation, the signal source used to drive the ON/OFF input must be able to swing above and below the specified turn-on/turn-off voltage thresholds which guarantee an ON or OFF state (see Electrical Characteristics).

The ON/OFF signal may come from either a totem-pole output, or an open-collector output with pull-up resistor to the LP2980 input voltage or another logic supply. The high-level voltage may exceed the LP2980 input voltage, but must remain within the Absolute Maximum Ratings for the ON/OFF pin.

applied to the ON/OFF input have a slew rate which is greater than 40mV/µs.

Important: the regulator shutdown function will operate incorrectly if a slow-moving signal is applied to the ON/OFF input

Micro SMD Mounting

The micro SMD package requires specific mounting techniques which are detailed in National Semiconductor Application Note # 1112. Referring to the section **Surface Mount Technology (SMT) Assembly Considerations**, it should be noted that the pad style which must be used with the 5-pin package is the NSMD (non-solder mask defined) type.

For best results during assembly, alignment ordinals on the PC board may be used to facilitate placement of the micro SMD device.

Micro SMD Light Sensitivity

Exposing the micro SMD device to direct sunlight will cause misoperation of the device. Light sources such as Halogen lamps can also affect electrical performance if brought near to the device.

The wavelenghts which have the most detrimental effect are reds and infra-reds, which means that the fluorescent lighting used inside most buildings has very little effect on performance. A micro SMD test board was brought to within 1 cm of a fluorescent desk lamp and the effect on the regulated output voltage was negligible, showing a deviation of less than 0.1% from nominal.



Typical Applications

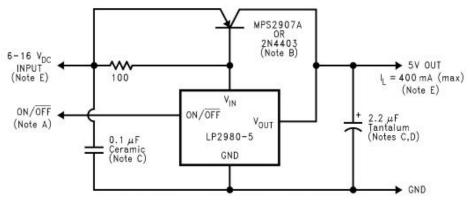


FIGURE 5. 5V/400mA Regulator

The LP2980 can be used to control higher-current regulators, by adding an external PNP pass device. With the PNP transistors shown in , the output current can be as high as 400mA, as long as the input voltage is held within the Safe Operation Boundary Curves shown below in.

To ensure regulation, the minimum input voltage of this regulator is 6V. This "headroom" is the sum of the VBE of the external transistor and the dropout voltage of the LP2980.

Notes:

A. Drive this input with a logic signal (see Application Hints). If the shutdown function is not to be used, tie the ON/OFF pin directly to the VIN pin.

B. Recommended devices (other PNP transistors can be used if the current gain and voltage ratings are similar).

C. Capacitor is required for regulator stability. Minimum size is shown, and may be increased without limit.

D. Increasing the output capacitance improves transient response and increases phase margin.

E. Maximum safe input voltage and load current are limited by power dissipation in the PNP pass transistor and the maximum ambient temperature for the specific application. If a TO-92 transistor such as the MPS2907A is used, the thermal resistance from junction-to-ambient is 180°C/W in still air.

Assuming a maximum allowable junction temperature of 150°C for the MPS2907A device, the following curves show the maximum VIN and IL values that may be safely used for several ambient temperatures.

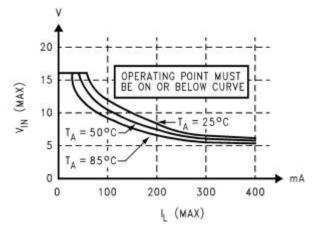
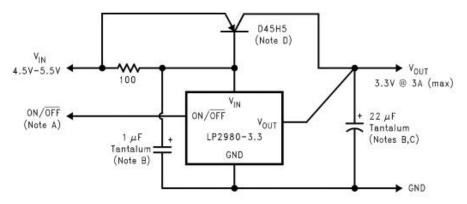
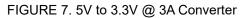


FIGURE 6. Safe Operation Boundary Curves for Figure 5







With limited input voltage range, the LP2980 can control a 3.3V, 3A regulator with the use of a high current-gain external PNP pass transistorias shown in . If the regulator is to be loaded with the full 3A, heat sinking will be required on the pass transistor to keep it within its rated temperature range. Refer to the Heatsink Thermal Resistance Requirements, below. For best load regulation at the high load current, the LP2980 output voltage connection should be made as close to the load as possible.

Although this regulator can handle a much higher load current than can the LP2980 alone, it can be shut down in the same manner as the LP2980. When the ON/OFF control is less than 1 µA from the source. Notes:

A. Drive this input with a logic signal (see Application Hints). If the shutdown function is not to be used, tie the ON/OFF pin directly to the VIN pin.

B. Capacitor is required for regulator stability. Minimum size is shown, and may be increased without limit.

C. Increasing the output capacitance improves transient response and increases phase margin.

D. A heatsink may be required for this transistor. The maximum allowable value for thermal resistance of the heatsink is dependent on ambient temperature and load current (see curves in). Once the value is obtained from the graph, a heatsink must be selected which has a thermal resistance equal to or lower than this value. If the value is above 60°C/W, no heatsink is required (the TO-220 package alone will safely dissipate this).

For these curves, a maximum junction temperature of 150°C is assumed for the pass transistor. The case to heatsink at

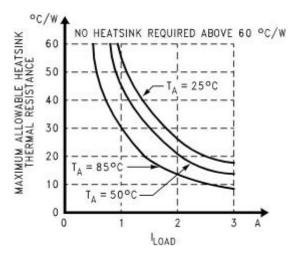
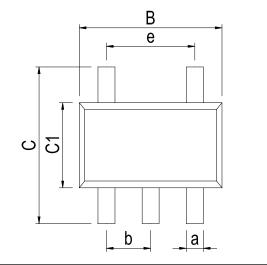


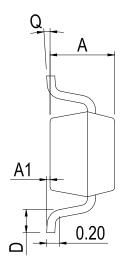
FIGURE 8. Heatsink Thermal Resistance Requirements for Figure 7



Physical Dimensions

SOT-23-5





Dimensions In Millimeters(SOT-23-5)										
Symbol:	A	A1	В	С	C1	D	Q	а	b	е
Min:	1.05	0.00	2.82	2.65	1.50	0.30	0°	0.30	- 0.95 BSC	1.90 BSC
Max:	1.15	0.15	3.02	2.95	1.70	0.60	8°	0.40		



Revision History

DATE	REVISION	PAGE
2014-6-24	New	1-18
2023-7-24	Update encapsulation type、Update Lead Temperature	1、3



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